

DOCKET: CU-3569

**IN THE UNITED STATES PATENT & TRADEMARK OFFICE**

APPLICANT: Kei MURAYAMA et al

TITLE: SEMICONDUCTOR DEVICE HAVING A CARBON  
FIBER REINFORCED RESIN AS A HEAT  
RADIATION PLATE HAVING A CONCAVE PORTION

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**PRELIMINARY AMENDMENT**

Dear Sir:

This is a preliminary amendment accompanying a new patent application being filed simultaneously herewith as a divisional application under 37 CFR 1.53(b).

Please amend this application as follows:

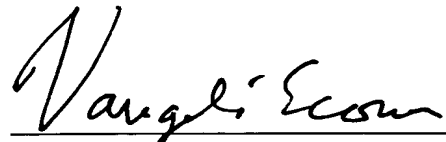
**IN THE SPECIFICATION:**

Page 1, after the title, insert the paragraph as shown on the attachment.

**PRIORITY**

It is noted that a certified copy of the Japanese priority application was submitted on May 23, 2001 in applicant's parent application, Serial No. 09/760,396.

Respectfully submitted,



Attorney for Applicant

February 12, 2004

Date

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